

## Excellent Integrated System Limited

Stocking Distributor

Click to view price, real time Inventory, Delivery & Lifecycle Information:

[Vishay Semiconductor/Diodes Division](#)  
[HFA08PB60](#)

For any questions, you can email us directly:

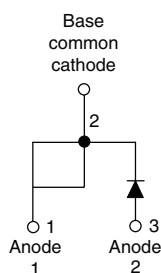
[sales@integrated-circuit.com](mailto:sales@integrated-circuit.com)



**HFA08PB60**

Vishay High Power Products

## HEXFRED® Ultrafast Soft Recovery Diode, 8 A



TO-247AC modified

### FEATURES

- Ultrafast recovery
- Ultrasoft recovery
- Very low  $I_{RRM}$
- Very low  $Q_{rr}$
- Specified at operating conditions
- Designed and qualified for industrial level

### BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

### DESCRIPTION

HFA08PB60 is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 8 A continuous current, the HFA08PB60 is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current ( $I_{RRM}$ ) and does not exhibit any tendency to "snap-off" during the  $t_b$  portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED HFA08PB60 is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

### PRODUCT SUMMARY

$V_R$	600 V
$V_F$ at 8 A at 25 °C	1.7 V
$I_{F(AV)}$	8 A
$t_{rr}$ (typical)	18 ns
$T_J$ (maximum)	150 °C
$Q_{rr}$ (typical)	65 nC
$dl_{(rec)M}/dt$ (typical) at 125 °C	210 A/μs
$I_{RRM}$ (typical)	3.5 A

### ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	$V_R$		600	V
Maximum continuous forward current	$I_F$	$T_C = 100\text{ °C}$	8	A
Single pulse forward current	$I_{FSM}$		60	
Maximum repetitive forward current	$I_{FRM}$		24	
Maximum power dissipation	$P_D$	$T_C = 25\text{ °C}$	36	W
		$T_C = 100\text{ °C}$	14	
Operating junction and storage temperature range	$T_J, T_{Stg}$		- 55 to + 150	°C

# HFA08PB60

Vishay High Power Products

HEXFRED®  
 Ultrafast Soft Recovery Diode, 8 A



ELECTRICAL SPECIFICATIONS (T <sub>J</sub> = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V <sub>BR</sub>	I <sub>R</sub> = 100 µA	600	-	-	V
Maximum forward voltage	V <sub>FM</sub>	I <sub>F</sub> = 8.0 A	-	1.4	1.7	
		I <sub>F</sub> = 16 A	-	1.7	2.1	
		I <sub>F</sub> = 8.0 A, T <sub>J</sub> = 125 °C	-	1.4	1.7	
Maximum reverse leakage current	I <sub>RM</sub>	V <sub>R</sub> = V <sub>R</sub> rated	-	0.3	5.0	µA
		T <sub>J</sub> = 125 °C, V <sub>R</sub> = 0.8 x V <sub>R</sub> rated	-	100	500	
Junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 200 V	-	10	25	pF
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from package body	-	8.0	-	nH

DYNAMIC RECOVERY CHARACTERISTICS (T <sub>J</sub> = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time See fig. 5, 10	t <sub>rr</sub>	I <sub>F</sub> = 1.0 A, dI <sub>F</sub> /dt = 200 A/µs, V <sub>R</sub> = 30 V	-	18	-	ns
	t <sub>rr1</sub>	T <sub>J</sub> = 25 °C	-	37	55	
	t <sub>rr2</sub>	T <sub>J</sub> = 125 °C	-	55	90	
Peak recovery current See fig. 6	I <sub>RRM1</sub>	T <sub>J</sub> = 25 °C	-	3.5	5.0	A
	I <sub>RRM2</sub>	T <sub>J</sub> = 125 °C	-	4.5	8.0	
Reverse recovery charge See fig. 7	Q <sub>rr1</sub>	T <sub>J</sub> = 25 °C	-	65	138	nC
	Q <sub>rr2</sub>	T <sub>J</sub> = 125 °C	-	124	360	
Peak rate of fall of recovery current during t <sub>b</sub> See fig. 8	dI <sub>(rec)</sub> /dt1	T <sub>J</sub> = 25 °C	-	240	-	A/µs
	dI <sub>(rec)</sub> /dt2	T <sub>J</sub> = 125 °C	-	210	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Lead temperature	T <sub>lead</sub>	0.063" from case (1.6 mm) for 10 s	-	-	300	°C
Thermal resistance, junction to case	R <sub>thJC</sub>		-	-	3.5	K/W
Thermal resistance, junction to ambient	R <sub>thJA</sub>	Typical socket mount	-	-	40	
Thermal resistance, case to heatsink	R <sub>thCS</sub>	Mounting surface, flat, smooth and greased	-	0.25	-	
Weight			-	6.0	-	g
			-	0.21	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style TO-247AC modified (JEDEC)	HFA08PB60			



# HFA08PB60

## HEXFRED® Ultrafast Soft Recovery Diode, 8 A

## Vishay High Power Products

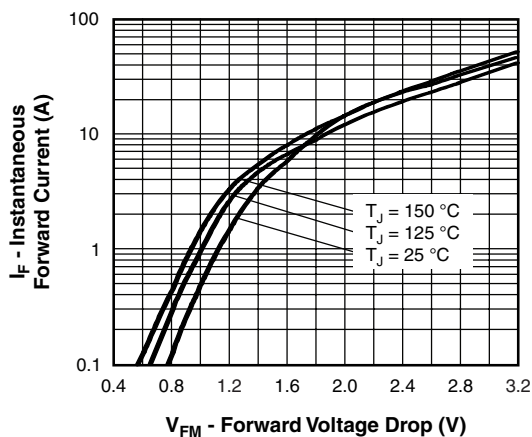


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

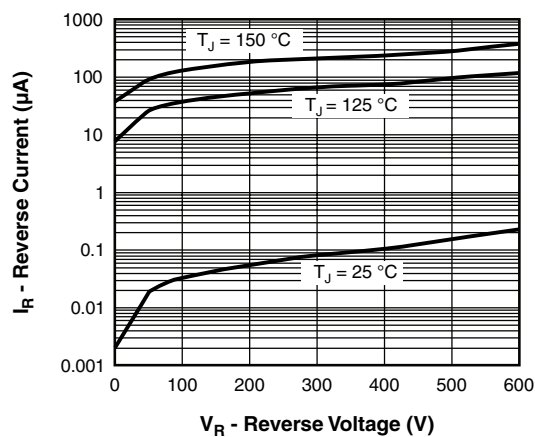


Fig. 2 - Typical Reverse Current vs. Reverse Voltage

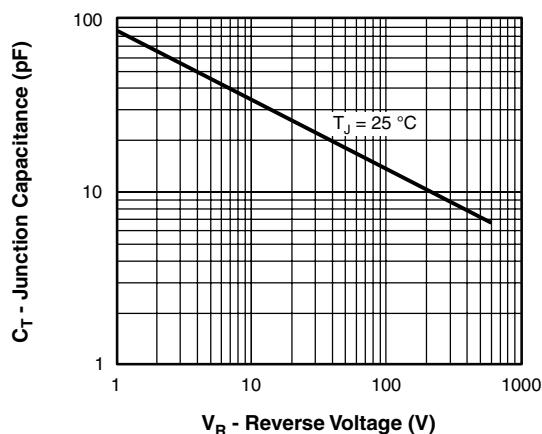


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

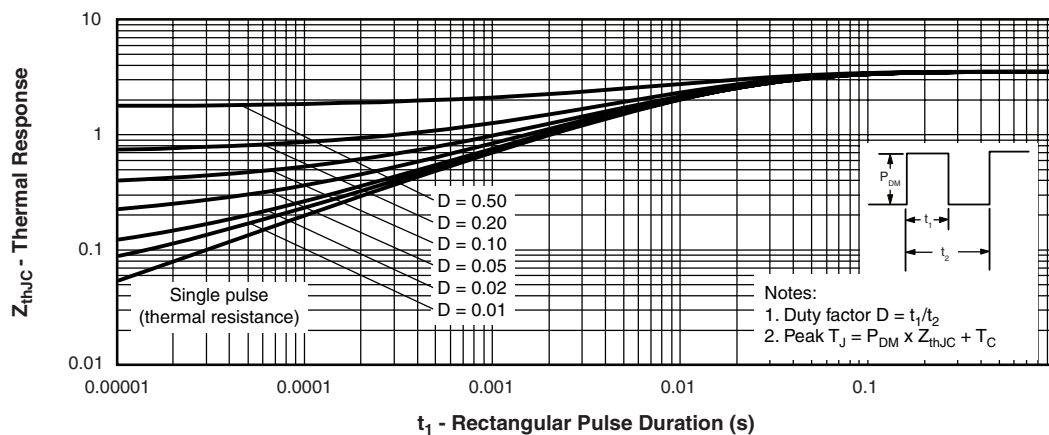


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics

## HFA08PB60

Vishay High Power Products

HEXFRED®  
Ultrafast Soft Recovery Diode, 8 A

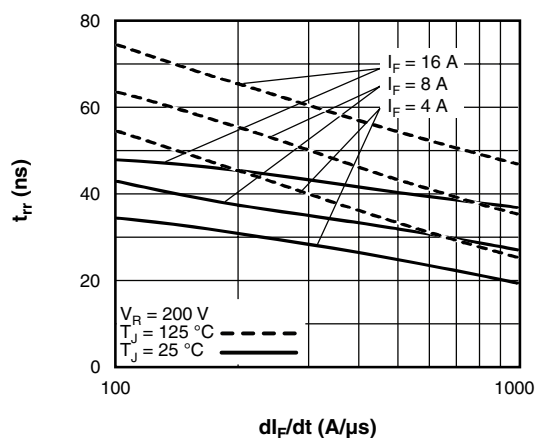


Fig. 5 - Typical Reverse Recovery Time vs.  $dI_F/dt$  (Per Leg)

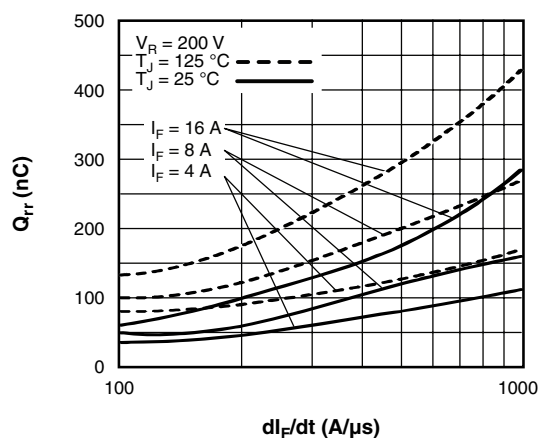


Fig. 7 - Typical Stored Charge vs.  $dI_F/dt$  (Per Leg)

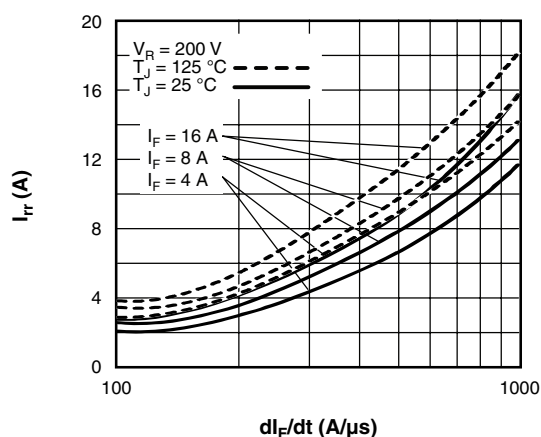


Fig. 6 - Typical Recovery Current vs.  $dI_F/dt$  (Per Leg)

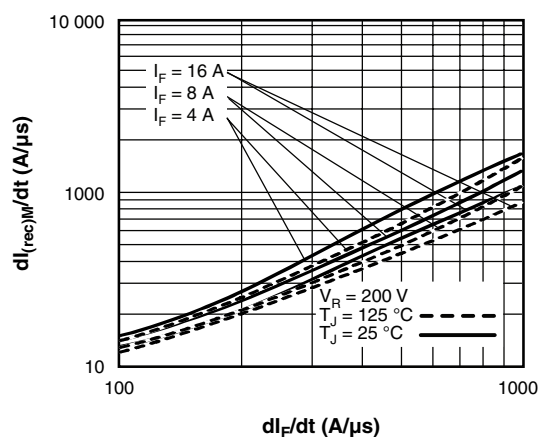


Fig. 8 - Typical  $dI_{(rec)M}/dt$  vs.  $dI_F/dt$  (Per Leg)



## HFA08PB60

### HEXFRED® Ultrafast Soft Recovery Diode, 8 A

Vishay High Power Products

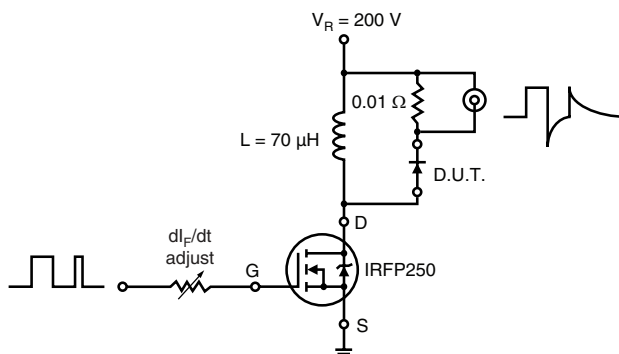


Fig. 9 - Reverse Recovery Parameter Test Circuit

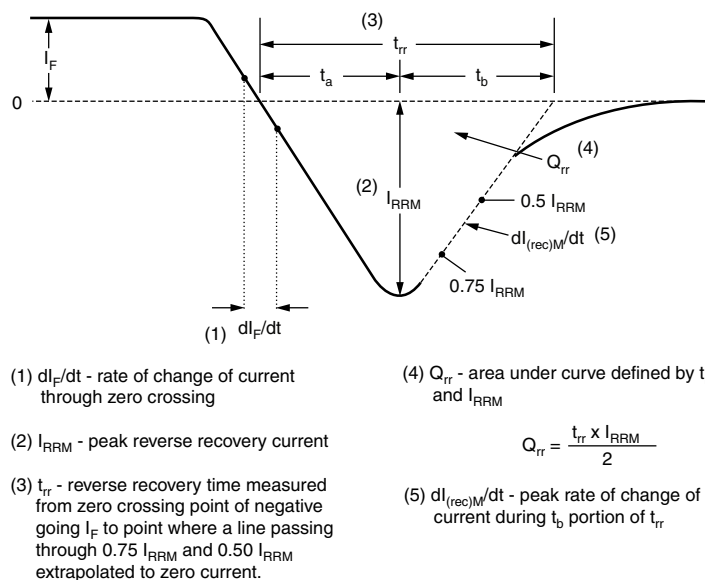


Fig. 10 - Reverse Recovery Waveform and Definitions

## HFA08PB60

Vishay High Power Products

HEXFRED®  
 Ultrafast Soft Recovery Diode, 8 A



### ORDERING INFORMATION TABLE

Device code	HF	A	08	PB	60	-
	1	2	3	4	5	6
1	- HEXFRED® family					
2	- Process designator: A = Electron irradiated B = Platinum diffused					
3	- Current rating (08 = 8 A)					
4	- Package outline (PB = TO-247, 2 pins)					
5	- Voltage rating (60 = 600 V)					
6	- • None = Standard production • PbF = Lead (Pb)-free					

LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?95253">http://www.vishay.com/doc?95253</a>
Part marking information	<a href="http://www.vishay.com/doc?95255">http://www.vishay.com/doc?95255</a>



## Legal Disclaimer Notice

Vishay

### Disclaimer

All product specifications and data are subject to change without notice.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained herein or in any other disclosure relating to any product.

Vishay disclaims any and all liability arising out of the use or application of any product described herein or of any information provided herein to the maximum extent permitted by law. The product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein, which apply to these products.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications unless otherwise expressly indicated. Customers using or selling Vishay products not expressly indicated for use in such applications do so entirely at their own risk and agree to fully indemnify Vishay for any damages arising or resulting from such use or sale. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

Product names and markings noted herein may be trademarks of their respective owners.